GD65232, GD75232 **MULTIPLE RS-232 DRIVERS AND RECEIVERS**

SLLS206H - MAY 1995 - REVISED JUNE 2002

Single Chip With Easy Interface Between **UART and Serial-Port Connector of IBM™ PC/AT and Compatibles**

- Meet or Exceed the Requirements of ANSI Standard TIA/EIA-232-F and ITU **Recommendation V.28**
- **Designed to Support Data Rates up to** 120 kbit/s
- Pinout Compatible With SN75C185 and SN75185

GD65232, GD75232...DB, DW, N, OR PW PACKAGE (TOP VIEW) V_{DD} 20 | Vcc RA1 1 2 19 **∏** RY1 RA2 | 3 18 ¶ RY2 RA3 [] 4 17 🛮 RY3 DY1 Π5 16 **∏** DA1 DY2 **∏**6 15 ∏ DA2 RA4 **[**] 7 14 | RY4 DY3 [8 13 **∏** DA3 12 N RY5 RA5 **1**9 V_{SS} [] 10 11 **∏** GND

description

The GD65232 and GD75232 combine three drivers and five receivers from the Texas Instruments trade-standard SN75188 and SN75189 bipolar quadruple drivers and receivers, respectively. The pinout matches the flow-through design of the SN75C185 to decrease the part count, reduce the board space required, and allow easy interconnection of the UART and serial-port connector of an IBM™ PC/AT and compatibles. The bipolar circuits and processing of the GD65232 and GD75232 provide a rugged, low-cost solution for this function at the expense of quiescent power and external passive components relative to the SN75C185.

The GD65232 and GD75232 comply with the requirements of the TIA/EIA-232-F and ITU (formerly CCITT) V.28 standards. These standards are for data interchange between a host computer and a peripheral at signaling rates up to 20 kbit/s. The switching speeds of these devices are fast enough to support rates up to 120 kbit/s with lower capacitive loads (shorter cables). Interoperability at the higher signaling rates cannot be expected unless the designer has design control of the cable and the interface circuits at both ends. For interoperability at signaling rates up to 120 kbit/s, use of ANSI TIA/EIA-423-B (ITU V.10) and TIA/EIA-422-B (ITU V.11) standards is recommended.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	GD65232N	GD65232N
-40°C to 85°C	SOIC - DW	Tube	GD65232DW	GD65232
	SOIC - DW	Tape and reel	GD65232DWR	GD65232
	SSOP – DB	Tape and reel	GD65232DBR	GD65232
	TSSOP – PW	Tape and reel	GD65232PWR	GD65232
	PDIP – N	Tube	GD75232N	GD75232N
	SOIC - DW	Tube	GD75232DW	GD75232
0°C to 70°C	301C - DVV	Tape and reel	GD75232DWR	GD75232
	SSOP – DB	Tape and reel	GD75232DBR	GD75232
	TSSOP – PW	Tape and reel	GD75232PWR	GD75232

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

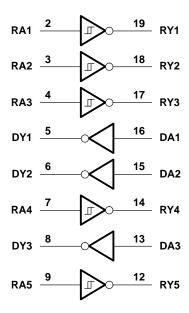


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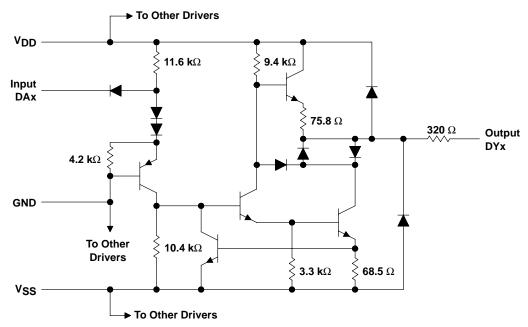
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logic diagram (positive logic)



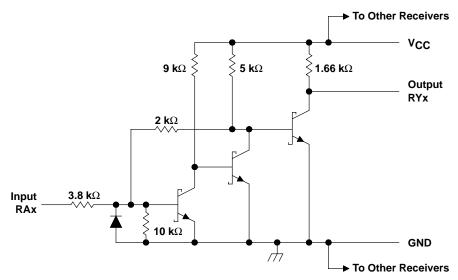
schematic (each driver)



Resistor values shown are nominal.



schematic (each receiver)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V _{CC}		10 V
V _{DD}		15 V
V _{SS}		–15 V
Input voltage range, V _I : Driver		\dots -15 V to 7 V
Receiver		30 V to 30 V
Driver output voltage range, V _O		–15 V to 15 V
Receiver low-level output current, IOL		20 mA
Package thermal impedance, θ_{JA} (see Note 2):	: DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	PW package	83°C/W
Lead temperature 1,6 mm (1/16 inch) from case	e for 10 seconds	260°C
Storage temperature range, T _{stq}		-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



NOTES: 1. All voltages are with respect to the network ground terminal.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{DD}	Supply voltage (see Note 3)		7.5	9	15	V
VSS	Supply voltage (see Note 3)		-7.5	-9	-15	V
Vcc	Supply voltage (see Note 3)		4.5	5	5.5	V
VIH	/IH High-level input voltage (driver only)					V
VIL	Low-level input voltage (driver only)				0.8	V
1	Lligh lovel cutout current	Driver			-6	mA
ЮН	High-level output current	Receiver			-0.5	ША
1	Low-level output current	Driver			6	mA
IOL	Low-level output current	Receiver			16	IIIA
TA	Operating free-air temperature	GD65232	-40		85	°C
I 'A	Operating free-air temperature GD7523		0	-	70	C

NOTE 3: When powering up the GD65232 and GD75232, the following sequence should be used:

- 1. V_{SS} 2. GND
- 3. V_{DD}
- 4. VCC
- 5. I/Os

 $Applying \ V_{CC} \ to \ the \ device \ before \ V_{DD} \ may \ allow \ large \ currents \ to \ flow, \ causing \ damage \ to \ the \ device. When \ powering \ down \ the$ GD65232 and GD75232, the reverse sequence should be used.

supply currents over recommended operating free-air temperature range

	PARAMETER		TEST CO	NDITIONS		MIN MAX	UNIT
			$V_{DD} = 9 V$,	V _{SS} = -9 V	15		
		All inputs at 1.9 V,	No load	$V_{DD} = 12 V$,	$V_{SS} = -12 \text{ V}$	19	
	Cumply ourrant from \/			$V_{DD} = 15 V$,	$V_{SS} = -15 \text{ V}$	25	_{mA}
IDD	Supply current from V _{DD}			V _{DD} = 9 V,	V _{SS} = -9 V	4.5	
		All inputs at 0.8 V,	No load	V _{DD} = 12 V,	$V_{SS} = -12 \text{ V}$	5.5	
				$V_{DD} = 15 V$,	$V_{SS} = -15 \text{ V}$	9	
		All inputs at 1.9 V,	No load	V _{DD} = 9 V,	$V_{SS} = -9 V$	-15	mA
				V _{DD} = 12 V,	$V_{SS} = -12 \text{ V}$	-19	
	Cumply ourrant from Vac			V _{DD} = 15 V,	V _{SS} = -15 V	-25	
Iss	Supply current from VSS		No load	V _{DD} = 9 V,	V _{SS} = -9 V	-3.2	
		All inputs at 0.8 V,		$V_{DD} = 12 V$,	$V_{SS} = -12 \text{ V}$	-3.2	
			$V_{DD} = 15 V$,	$V_{SS} = -15 \text{ V}$	-3.2		
laa	Supply current from Vo.a	All inputs at 5 V	No load,	Vaa = 5 V	GD65232	38	mA
ICC	Supply current from V _{CC}	All inputs at 5 V,	ino ioau,	V _{CC} = 5 V	GD75232	30	IIIA

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DRIVER SECTION

electrical characteristics over recommended operating free-air temperature range, V_{DD} = 9 V, V_{SS} = -9 V, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
Vон	High-level output voltage	$V_{IL} = 0.8 V$,	$R_L = 3 k\Omega$,	See Figure 1	6	7.5		V
VOL	Low-level output voltage (see Note 4)	V _{IH} = 1.9 V,	$R_L = 3 k\Omega$,	See Figure 1		-7.5	-6	V
ΙΗ	High-level input current	V _I = 5 V,	See Figure 2				10	μΑ
Ι _Ι L	Low-level input current	$V_{I} = 0,$	See Figure 2				-1.6	mA
I _{OS(H)}	High-level short-circuit output current (see Note 5)	V _{IL} = 0.8 V,	V _O = 0,	See Figure 1	-4.5	-12	-19.5	mA
IOS(L)	Low-level short-circuit output current	V _{IH} = 2 V,	V _O = 0,	See Figure 1	4.5	12	19.5	mA
r _O	Output resistance (see Note 6)	VCC = VDD =	V _{SS} = 0,	$V_O = -2 V \text{ to } 2 V$	300		, and the second	Ω

- NOTES: 4. The algebraic convention, where the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic levels only (e.g., if –10 V is maximum, the typical value is a more negative voltage).
 - 5. Output short-circuit conditions must maintain the total power dissipation below absolute maximum ratings.
 - 6. Test conditions are those specified by TIA/EIA-232-F and as listed above.

switching characteristics, V_{CC} = 5 V, V_{DD} = 12 V, V_{SS} = -12 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	C _L = 15 pF,	See Figure 3		315	500	ns
tPHL	Propagation delay time, high- to low-level output	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	C _L = 15 pF,	See Figure 3		75	175	ns
+	Transition time,	$R_1 = 3 k\Omega \text{ to } 7 k\Omega$	$C_L = 15 pF$,	See Figure 3		60	100	ns
^t TLH	low- to high-level output	K_ = 3 K22 to 7 K22	$C_L = 2500 \text{ pF},$	See Figure 3 and Note 7		1.7	2.5	μs
+	Transition time,	$R_1 = 3 k\Omega$ to $7 k\Omega$	$C_L = 15 pF$,	See Figure 3		40	75	ns
tTHL	high- to low-level output	V = 2 K22 (0 / K22	$C_L = 2500 \text{ pF},$	See Figure 3 and Note 7		1.5	2.5	μs

NOTE 7: Measured between ±3-V and ±3-V points of the output waveform (TIA/EIA-232-F conditions); all unused inputs are tied either high or low.

RECEIVER SECTION

electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TES	ST CONDITIONS		MIN	TYP [†]	MAX	UNIT
\/	Desitive seins input threehold valtese	T _A = 25°C,	See Figure 5		1.75	1.9	2.3	V
VIT+	Positive-going input threshold voltage	$T_A = 0$ °C to 70 °C,	See Figure 5		1.55		2.3	V
VIT-	Negative-going input threshold voltage				0.75	0.97	1.25	V
V _{hys}	Input hysteresis voltage (V _{IT+} – V _{IT})				0.5			V
V	High level cutout voltage	Jan. 0.5 mA	V _{IH} = 0.75 V		2.6	4	5	V
VOH	High-level output voltage	$I_{OH} = -0.5 \text{ mA}$	Inputs open		2.6			V
VOL	Low-level input voltage	I _{OL} = 10 mA,	V _I = 3 V			0.2	0.45	V
		\/. 2E\/	Coo Figuro F	GD65232	3.6		11	
lіН	High-level input current	$V_{I} = 25 V$,	See Figure 5	GD75232	3.6	-	8.3	mA
		V _I = 3 V,	See Figure 5		0.43	-		
		V: 05.V	$V_{I} = -25 \text{ V},$ See Figure 5	GD65232	-3.6		-11	
I _{IL}	Low-level output current	$V_{\parallel} = -25 \text{ V},$		GD75232	-3.6		-8.3	mA
		V _I = −3 V,	See Figure 5		-0.43			
los	Short-circuit output current	See Figure 4				-3.4	-12	mA

[†] All typical values are at $T_A = 25^{\circ}C$, $V_{CC} = 5$ V, $V_{DD} = 9$ V, and $V_{SS} = -9$ V.

switching characteristics, V_{CC} = 5 V, V_{DD} = 12 V, V_{SS} = -12 V, T_A = 25 $^{\circ}$ C

	PARAMETER		TEST CONDITIONS			TYP	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output					107	250	ns
tPHL	Propagation delay time, high- to low-level output	$C_1 = 50 pF$	$R_1 = 5 k\Omega$	See Figure 6		42	150	ns
tTLH	Transition time, low- to high-level output	CL = 50 pr,	KL = 5 K22,	See Figure 6		175	350	ns
^t THL	Transition time, high- to low-level output					16	60	ns
tPLH	Propagation delay time, low- to high-level output					100	160	ns
tPHL	Propagation delay time, high- to low-level output	C 15 pE	D: -15k0	Coo Figuro 6		60	100	ns
tTLH	Transition time, low- to high-level output	$C_L = 15 pF$,	$RL = 1.5 \text{ K}_{2}$	See Figure 6		90	175	ns
^t THL	Transition time, high- to low-level output					15	50	ns



PARAMETER MEASUREMENT INFORMATION

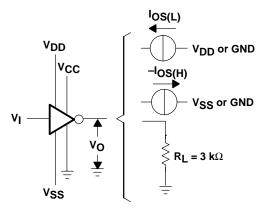


Figure 1. Driver Test Circuit for V_{OH} , V_{OL} , $I_{OS(H)}$, and $I_{OS(L)}$

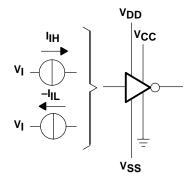
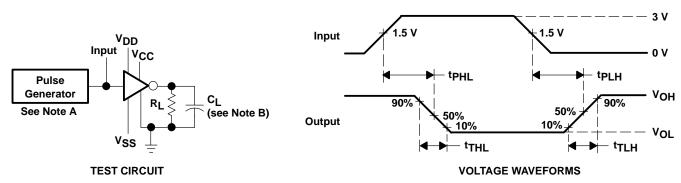


Figure 2. Driver Test Circuit for IIH and IIL



NOTES: A. The pulse generator has the following characteristics: t_W = 25 μ s, PRR = 20 kHz, Z_O = 50 Ω , t_f = t_f < 50 ns.

B. C_L includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

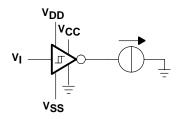


Figure 4. Receiver Test Circuit for IOS

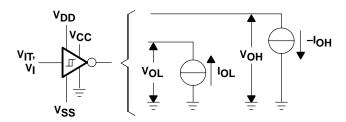
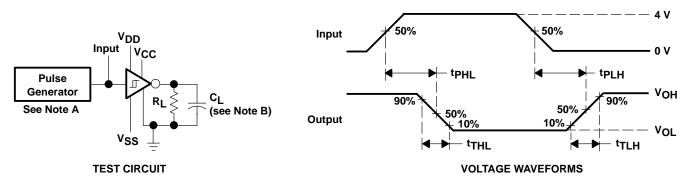


Figure 5. Receiver Test Circuit for V_{IT} , V_{OH} , and V_{OL}



NOTES: A. The pulse generator has the following characteristics: t_W = 25 μ s, PRR = 20 kHz, Z_O = 50 Ω , t_f = t_f < 50 ns.

B. C_L includes probe and jig capacitance.

Figure 6. Receiver Propagation and Transition Times

TYPICAL CHARACTERISTICS DRIVER SECTION

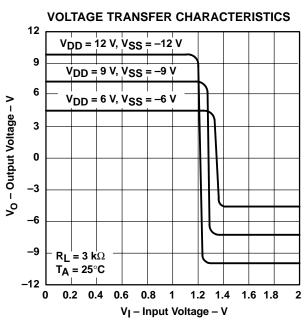


Figure 7

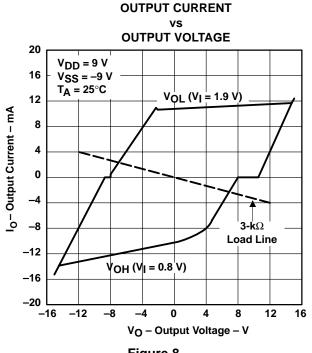
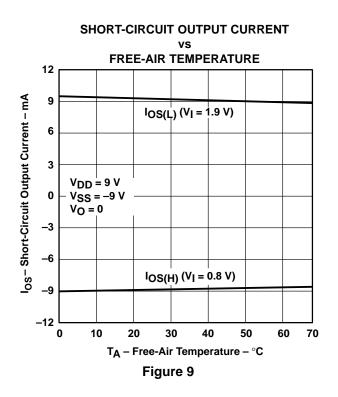
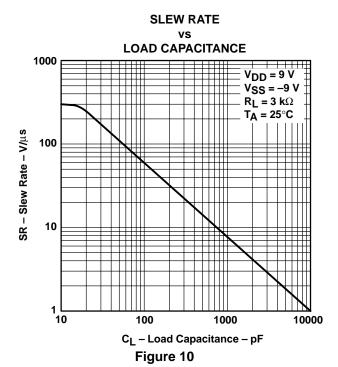
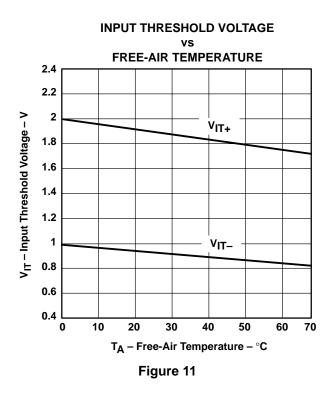


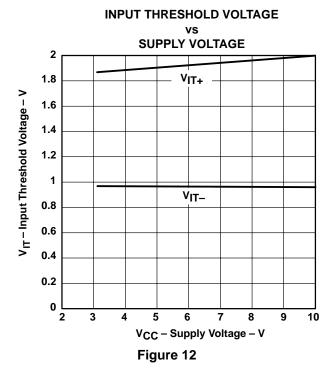
Figure 8

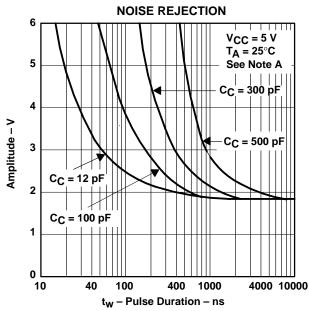


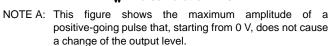


TYPICAL CHARACTERISTICS

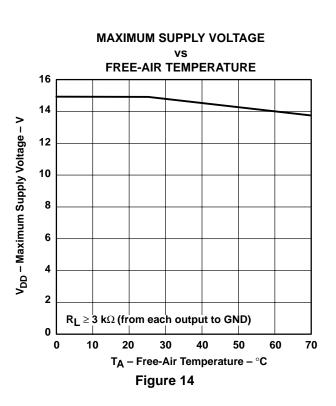














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APPLICATION INFORMATION

Diodes placed in series with the V_{DD} and V_{SS} leads protect the GD65232 and GD75232 in the fault condition in which the device outputs are shorted to ± 15 V and the power supplies are at low and provide low-impedance paths to ground (see Figure 15).

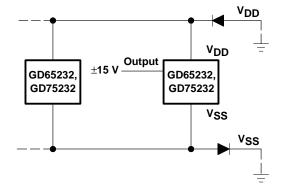


Figure 15. Power-Supply Protection to Meet Power-Off Fault Conditions of TIA/EIA-232-F

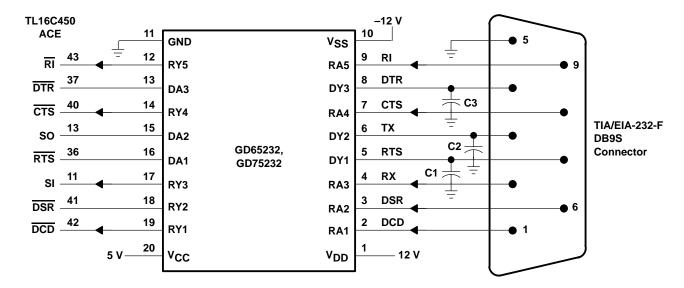


Figure 16. Typical Connection

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